

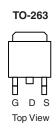
# P-Channel 60-V (D-S) 175 °C MOSFET

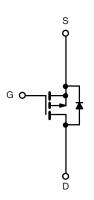
PRODUCT S	PRODUCT SUMMARY			
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>d</sup>		
- 60	0.0065 at V <sub>GS</sub> = - 10 V	- 110		
- 60	$0.0085 \text{ at V}_{GS} = -4.5 \text{ V}$	- 110		

### **FEATURES**

- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- 100 % R<sub>g</sub> Tested







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_C = 2$	25 °C, unless other	wise noted		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V <sub>DS</sub>	- 60	V
Gate-Source Voltage		V <sub>GS</sub>	± 20	7 v
Continuous Drain Current <sup>d</sup>	T <sub>C</sub> = 25 °C	I-	- 110	
$(T_J = 175  ^{\circ}C)$	T <sub>C</sub> = 125 °C	l <sub>D</sub> –	- 75	] A
Pulsed Drain Current	<u>'</u>		- 200	
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	- 85	
Single Pulse Avalanche Energy <sup>d</sup>	L = 0.1 IIII	E <sub>AS</sub>	211	mJ
	T <sub>C</sub> = 25 °C	В	272 <sup>c</sup>	14/
Maximum Power Dissipation	T <sub>A</sub> = 25 °C <sup>b</sup>	P <sub>D</sub>	3.75 <sup>b</sup>	W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 175	°C

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Limit	Unit
Junction-to-Ambient	PCB Mount <sup>d</sup>	$R_{thJA}$	40	°C/W
Junction-to-Case		$R_{thJC}$	0.55	C/VV

#### Notes

- a. Duty cycle  $\leq$  1 %.
- b. When Mounted on 1" square PCB (FR-4 material).
- c. See SOA curve for voltage derating.
- d. Limited by Package.

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<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V			- 1	μΑ	
	I <sub>DSS</sub>	V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			- 50		
		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			- 250	1	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 120			Α	
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A		0.0065			
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 125 °C		0.0129		1	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 175 °C		0.016		Ω	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A		0.0085			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 50 A	20			S	
Dynamic <sup>b</sup>	L			<u> </u>			
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = - 25 V, f = 1 MHz		9200		pF	
Output Capacitance	C <sub>oss</sub>			975			
Reverse Transfer Capacitance	C <sub>rss</sub>	1		760			
Total Gate Charge <sup>c</sup>	Qg			160	240	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>qs</sub>	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 110 A		40			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>	1		36			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	1.5	3	4.5	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			20	30		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -30 \text{ V, R}_{L} = 0.27 \Omega$		190	285	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong -110 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 2.5 \Omega$		140	210		
Fall Time <sup>c</sup>	t <sub>f</sub>	1		300	450		
Source-Drain Diode Ratings and Cha	·			000	100		
Continuous Current	Is				- 110		
Pulsed Current	I <sub>SM</sub>				- 200	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = - 50 A, V <sub>GS</sub> = 0 V		- 1.0	- 1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	. 33		60	90	ns	
Peak Reverse Recovery Charge	I <sub>RM(REC)</sub>	I <sub>F</sub> = - 50 A, di/dt = 100 A/μs		- 3	- 4.5	A	
Reverse Recovery Charge	Q <sub>rr</sub>	1		0.09	0.2	μC	

### Notes:

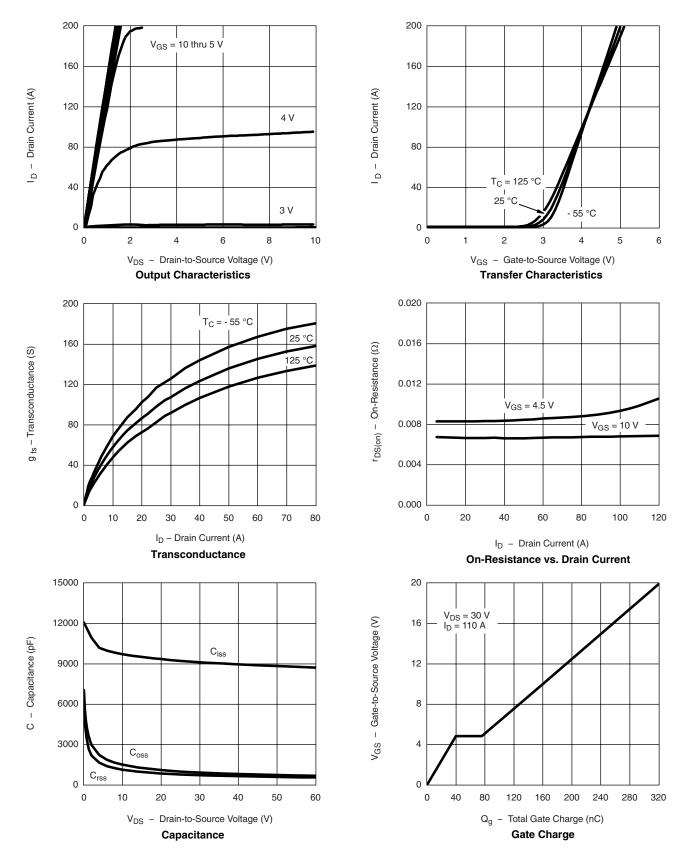
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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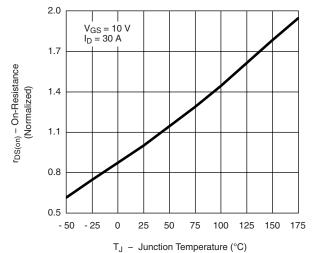


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

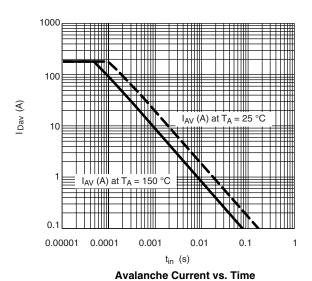


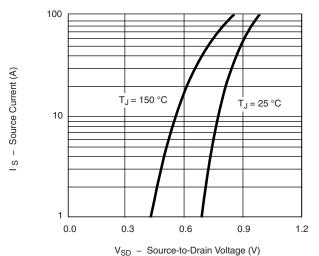


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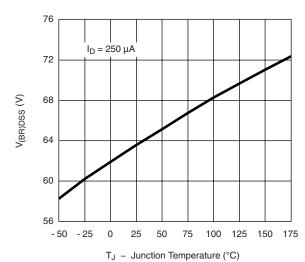


On-Resistance vs. Junction Temperature





Source-Drain Diode Forward Voltage

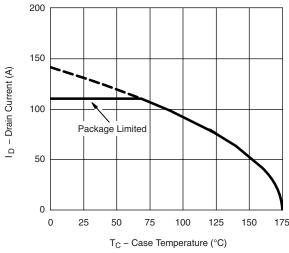


Drain Source Breakdown vs.
Junction Temperature

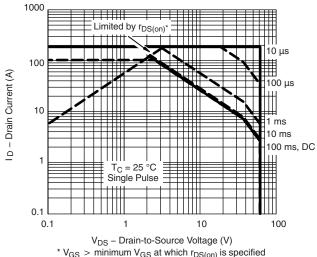
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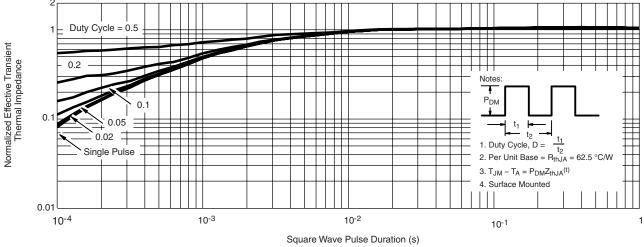
### THERMAL RATINGS



**Maximum Avalanche and Drain Current** vs. Case Temperature



 $^*$   $V_{\mbox{\footnotesize{GS}}}$  > minimum  $V_{\mbox{\footnotesize{GS}}}$  at which  $r_{\mbox{\footnotesize{DS(on)}}}$  is specified Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

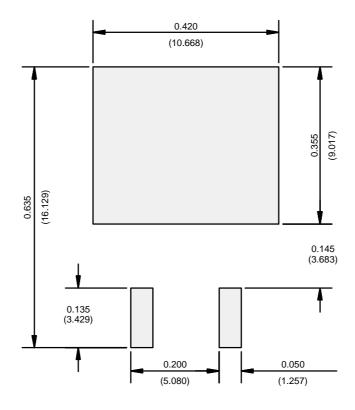
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## RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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